

	1	2	3	4	5	6
	1	2	3	4	5	6
А						
	H1	H2				
	H3 H3 NY PMS 440 0825 PH	$ \begin{array}{c} H4 \\ \begin{array}{c} H2 \\ \hline 0 \\ 198525 PH \end{array} $				
	1902С NY РМЅ 440 0025 РН	₩ 1902С NY PMS 440 0025 PH				
	PCB: PMP7935	РСВ				
		PCB LOGO Texas Instruments				
	PMP7935 REV B					
	H7 H7 NY PMS 440 8625 PH	H8 H8 NY PMS 440 0025 PH				
В						
	FID1 FID2 FID3	FID4     FID5     FID6				
	FID1 FID2 FID3	FID4 FID5 FID6				

LBL1 PCB Label Size: 0.65" x 0.20 "

ZZ1 Label Assembly Note This Assembly Note is for PCB labels only

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ZZ2 Assembly Note These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

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ZZ4
<u>Assembly Note</u> These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

				Number: PMP10740 F	Re
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lic	ensors do not warrant that the desig	n is production worthy. You should completely validate and test your des	ign implementation to confirm the system functionality for your application.	Engineer: Robert Sheehar	n
	2	3	Δ		
	2	5	7		

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	Designed for: Public Release	Mod. Date: 8/4/2015	_
	Project Title: LM27403 Buck		TEXAS
Rev: A	Sheet Title: Hardware		INSTRUMENTS
ntrol disabled	Assembly Variant: 001	Sheet: 2 of 2	in official interaction
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